

# 2SD1273, 2SD1273A

## Silicon NPN triple diffusion planar type

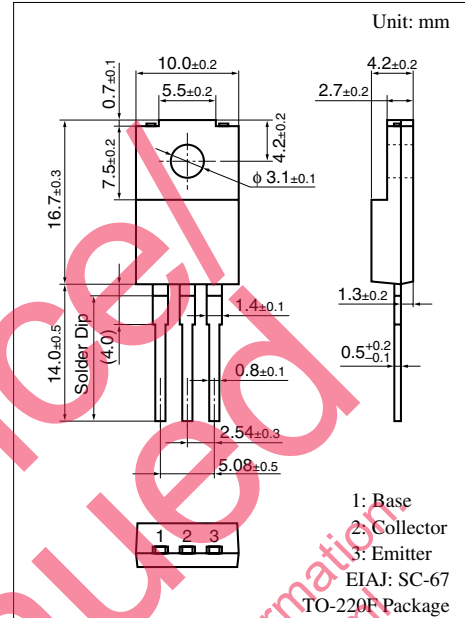
For power amplification with high forward current transfer ratio  
Complementary to 2SB1299

### ■ Features

- High forward current transfer ratio  $h_{FE}$
- Satisfactory linearity of forward current transfer ratio  $h_{FE}$
- Full-pack package which can be installed to the heat sink with one screw

### ■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector to base voltage	$V_{CBO}$	2SD1273 80	V
2SD1273A 100			
Collector to emitter voltage	$V_{CEO}$	2SD1273 60	V
2SD1273A 80			
Emitter to base voltage	$V_{EBO}$	6	V
Peak collector current	$I_{CP}$	6	A
Collector current	$I_C$	3	A
Base current	$I_B$	1	A
Collector power dissipation		$T_C = 25^\circ\text{C}$ 40	W
		$T_a = 25^\circ\text{C}$ 2	
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$



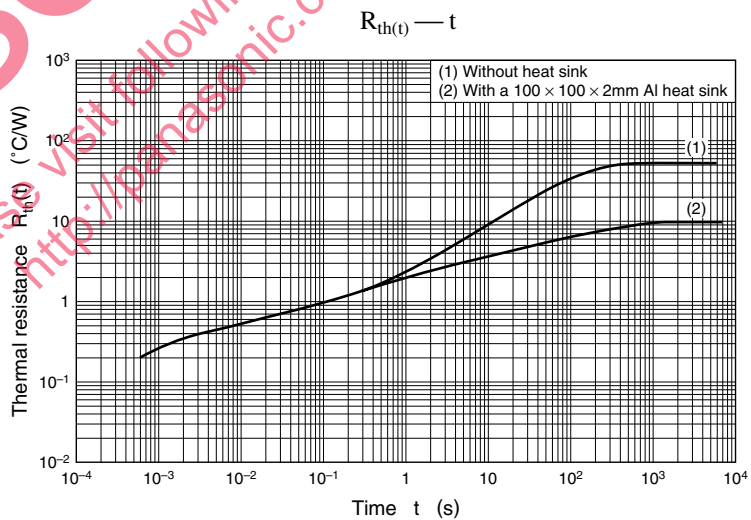
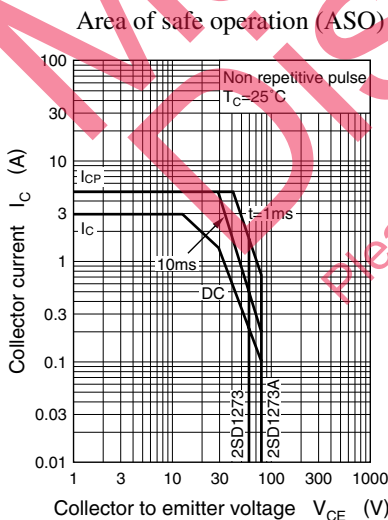
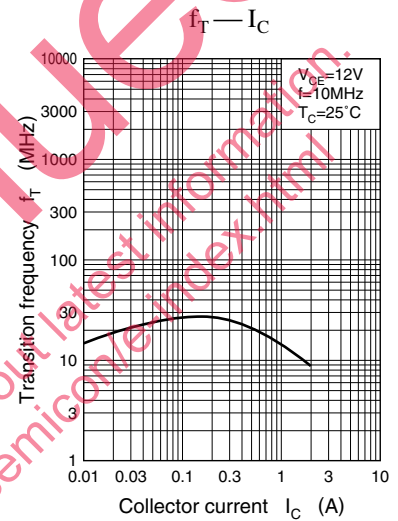
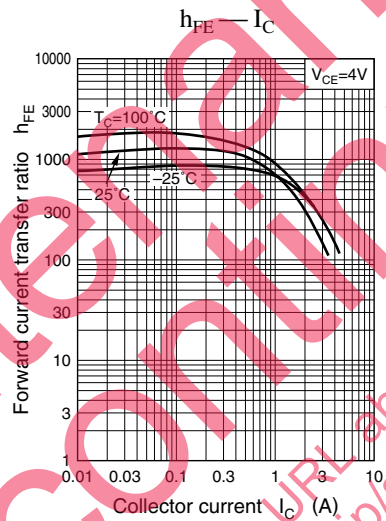
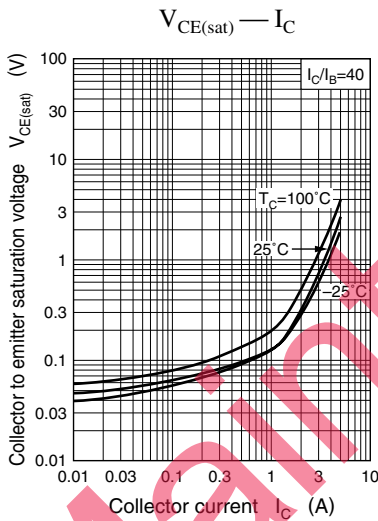
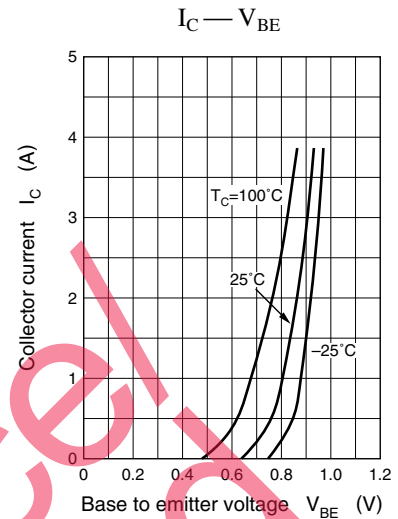
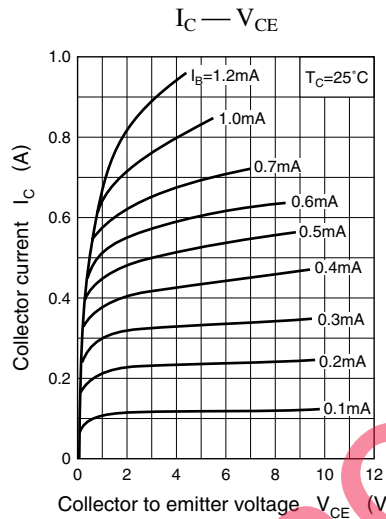
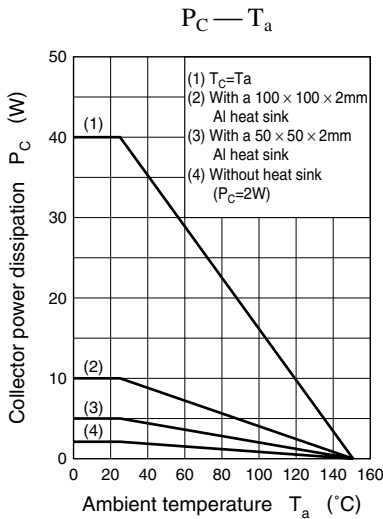
### ■ Electrical Characteristics $T_C = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector cutoff current	$I_{CBO}$	$V_{CB} = 80\text{ V}, I_E = 0$			100	$\mu\text{A}$
		$V_{CB} = 100\text{ V}, I_E = 0$			100	
Collector cutoff current	$I_{CEO}$	$V_{CE} = 40\text{ V}, I_B = 0$			100	$\mu\text{A}$
Emitter cutoff current	$I_{EBO}$	$V_{CB} = 6\text{ V}, I_C = 0$			100	$\mu\text{A}$
Collector to emitter voltage	$V_{CEO}$	$I_C = 25\text{ mA}, I_B = 0$	2SD1273 60			V
			2SD1273A 80			
Forward current transfer ratio *	$h_{FE}$	$V_{CE} = 4\text{ V}, I_C = 0.5\text{ A}$	500		2 500	
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = 2\text{ A}, I_B = 0.05\text{ A}$			1	V
Transition frequency	$f_T$	$V_{CE} = 12\text{ V}, I_C = 0.2\text{ A}, f = 10\text{ MHz}$		50		MHz

Note) \*: Rank classification

Rank	Q	P	O
$h_{FE}$	500 to 1 000	800 to 1 500	1 200 to 2 500

Ordering can be made by the common rank (PQ rank  $h_{FE} = 500$  to 1 500) in the rank classification.



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